

<b>L Number</b>	<b>Hits</b>	<b>Search Text</b>	<b>DB</b>	<b>Time stamp</b>
1	1	("5071792").PN.	USPAT; US-PGPUB	2002/11/16 22:12
2	0	pressing adj while with wax	USPAT; US-PGPUB	2002/11/16 22:13
3	8	pressing with harden\$ with wax	USPAT; US-PGPUB	2002/11/16 23:10
4	234	dry adj chemical adj etching	USPAT; US-PGPUB	2002/11/17 00:02
5	30615	adhesive adj tape	USPAT; US-PGPUB	2002/11/17 00:02
6	187676	cure curing cured	USPAT; US-PGPUB	2002/11/17 00:02
7	673	(adhesive adj tape) with (cure curing cured)	USPAT; US-PGPUB	2002/11/17 00:02
8	113924	wafer	USPAT; US-PGPUB	2002/11/17 00:03
9	29	((adhesive adj tape) with (cure curing cured)) with wafer	USPAT; US-PGPUB	2002/11/17 00:03
10	1111609	@ad>19950726 @rlad>19950726	USPAT; US-PGPUB	2002/11/17 00:03
11	9	((adhesive adj tape) with (cure curing cured)) with wafer) not (@ad>19950726 @rlad>19950726)	USPAT; US-PGPUB	2002/11/17 01:12
12	1340365	semiconductor integrated adj circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 01:13
13	19995	support\$ adj substrate	USPAT; US-PGPUB	2002/11/17 01:14
14	1703	pin! adj block	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 01:22
15	1268500	dissolv\$ solvent	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 01:15
16	14	(semiconductor integrated adj circuit) with (support\$ adj substrate) with (dissolv\$ solvent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 01:15
17	6	((semiconductor integrated adj circuit) with (support\$ adj substrate) with (dissolv\$ solvent)) not (@ad>19950726 @rlad>19950726)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 01:17

18	1796653	block	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 01:18
19	6	(support\$ adj substrate) with (dissolv\$ solvent) with block	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 01:18
21	11013	(dissolv\$ solvent) with block	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 01:19
22	584	((dissolv\$ solvent) with block) and (semiconductor integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 01:19
23	19	((dissolv\$ solvent) with block) with pin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 01:20
24	3	((((dissolv\$ solvent) with block) with pin) and (semiconductor integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 01:22
25	366	irvine.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 01:22
26	1	irvine.as. and (pin! adj block)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/17 01:22
27	2	("5202754") or ("5393706")).PN.	USPAT; US-PGPUB	2002/11/17 01:54
28	15	("3564358"   "3679941"   "4525921"   "4612083"   "4646627"   "4717448"   "4807021"   "4829018"   "4937659"   "4939568"   "4954458"   "4954875"   "4967393"   "4989063"   "5091762").PN.	USPAT	2002/11/17 01:52
29	15	("3564358"   "3679941"   "4525921"   "4612083"   "4646627"   "4717448"   "4807021"   "4829018"   "4937659"   "4939568"   "4954458"   "4954875"   "4967393"   "4989063"   "5091762").PN.	USPAT	2002/11/17 01:53

30	0	9925019.URPN.	USPAT	2002/11/17 01:53
31	0	("21 and 25").PN.	USPAT;	2002/11/17
32	0	((dissolv\$ solvent) with block) and irvine.as.	US-PGPUB	01:55
-	1	("6083811").PN.	USPAT;	2002/11/17
-	24	((("5681757") or ("5925924") or ("6083811") or ("5162251") or ("6120352") or ("5527744") or ("5552345") or ("5268065") or ("5081063") or ("5872046") or ("5597767") or ("3556075") or ("5185292") or ("5927993") or ("5071792") or ("4722130") or ("5605489") or ("5807787") or ("4023260") or ("5185292") or ("5434094") or ("4266334") or ("5480482") or ("5733814") or ("5302554"))).PN.	US-PGPUB	01:55
-	23	("3559282"   "3924323"   "5071792"   "5081061"   "5219796"   "5266528"   "5268065"   "5273940"   "5275958"   "5302554"   "5314844"   "5324687"   "5352249"   "5362681"   "5369060"   "5457072"   "5478782"   "5500389"   "5527744"   "5552345"   "5597767"   "5804495"   "5888883").PN.	USPAT	2002/11/16 21:50
-	17	((("3559282"   "3924323"   "5071792"   "5081061"   "5219796"   "5266528"   "5268065"   "5273940"   "5275958"   "5302554"   "5314844"   "5324687"   "5352249"   "5362681"   "5369060"   "5457072"   "5478782"   "5500389"   "5527744"   "5552345"   "5597767"   "5804495"   "5888883").PN.) not (((("5681757") or ("5925924") or ("6083811") or ("5162251") or ("6120352") or ("5527744") or ("5552345") or ("5268065") or ("5081063") or ("5872046") or ("5597767") or ("3556075") or ("5185292") or ("5927993") or ("5071792") or ("4722130") or ("5605489") or ("5807787") or ("4023260") or ("5185292") or ("5434094") or ("4266334") or ("5480482") or ("5733814") or ("5302554"))).PN.)	USPAT; US-PGPUB	2002/11/13 21:04
-	2	"05074934"	EPO; JPO; DERWENT	2002/11/13 21:29
-	1	1993-138354.NRAN.	DERWENT	2002/11/13 21:25
-	3	"3043903"	EPO; JPO; DERWENT	2002/11/13 21:26
-	2	("3043903").PN.	EPO; DERWENT	2002/11/13 21:27

-	0	tanaka-noboyuki.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 21:30
-	781	tanaka-nobuyuki.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 21:30
-	750	tanaka-nobuyuki.in. not (@ad>19950726 @rlad>19950726)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 21:31
-	1690271	dicing dice diced scribe scribing scribed cut cutting saw sawing sawed	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 21:32
-	48	(tanaka-nobuyuki.in. not (@ad>19950726 @rlad>19950726)) and (dicing dice diced scribe scribing scribed cut cutting saw sawing sawed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/13 22:18
-	1	("5480842").PN.	USPAT; US-PGPUB	2002/11/13 22:25
-	751	backlap\$ backgrind\$ back! adj (lap lapped lapping grind grinding)	USPAT; US-PGPUB	2002/11/14 19:51
-	845752	dicing dice diced scribe scribing scribed cut cutting saw sawing sawed	USPAT; US-PGPUB	2002/11/14 19:43
-	61	(backlap\$ backgrind\$ back! adj (lap lapped lapping grind grinding)) same (dicing dice diced scribe scribing scribed cut cutting saw sawing sawed) not (@ad>19950726 @rlad>19950726)	USPAT; US-PGPUB	2002/11/14 18:26
-	8	4023260.URPN.	USPAT	2002/11/14 17:39
-	8	4023260.URPN.	USPAT	2002/11/14 17:39
-	14	("4023260"   "4722130"   "4904610"   "4978639"   "5071792"   "5072280"   "5091331"   "5130276"   "5185292"   "5480842"   "5597766"   "5714405"   "5888883"   "5994205").PN.	USPAT	2002/11/14 17:40
-	84	backlap\$ backgrind\$ back! adj (lap lapped lapping grind grinding)	EPO; JPO	2002/11/14 19:43
-	341178	dicing dice diced scribe scribing scribed cut cutting saw sawing sawed	EPO; JPO	2002/11/14 19:43
-	25	(backlap\$ backgrind\$ back! adj (lap lapped lapping grind grinding)) and (dicing dice diced scribe scribing scribed cut cutting saw sawing sawed)	EPO; JPO	2002/11/14 19:43

-	485	(backlap\$ backgrind\$ back! adj (lap lapped lapping grind grinding)) and (dicing dice diced scribe scribing scribed cut cutting saw sawing sawed)	USPAT; US-PGPUB	2002/11/14 19:51
-	213	((backlap\$ backgrind\$ back! adj (lap lapped lapping grind grinding)) and (dicing dice diced scribe scribing scribed cut cutting saw sawing sawed)) not (@ad>19950726 @riad>19950726)	USPAT; US-PGPUB	2002/11/14 19:51
-	81	wafer and (((backlap\$ backgrind\$ back! adj (lap lapped lapping grind grinding)) and (dicing dice diced scribe scribing scribed cut cutting saw sawing sawed)) not (@ad>19950726 @riad>19950726))	USPAT; US-PGPUB	2002/11/14 20:03
-	1	"05074934"	USPAT; US-PGPUB	2002/11/14 20:05
-	1	"5074934"	USPAT; US-PGPUB	2002/11/14 20:05
-	1	"5" adj "74934"	USPAT; US-PGPUB	2002/11/14 20:09
-	14	("4023260"   "4722130"   "4904610"   "4978639"   "5071792"   "5072280"   "5091331"   "5130276"   "5185292"   "5480842"   "5597766"   "5714405"   "5888883"   "5994205").PN.	USPAT	2002/11/14 20:06
-	9	("3040489"   "3488835"   "3633269"   "3636618"   "3727282"   "4321747"   "4445956"   "4451972"   "4519168").PN.	USPAT	2002/11/14 20:07
-	7	3488835.URPN.	USPAT	2002/11/14 20:09
-	20	4722130.URPN.	USPAT	2002/11/14 20:09
-	4	4722130.URPN. not (@ad>19950726 @riad>19950726)	USPAT; US-PGPUB	2002/11/15 09:22
-	8	4023260.URPN.	USPAT	2002/11/14 20:10
-	11	("3393349"   "3797102"   "4017341"   "4567646"   "4851078"   "4857387"   "4962056"   "5051378"   "5091330"   "5096854"   "5420064").PN.	USPAT	2002/11/14 20:12
-	17	5051378.URPN.	USPAT	2002/11/14 20:16
-	257	(pin! adj block) and (semiconductor integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 09:24
-	1239	pin! adj block	USPAT; US-PGPUB	2002/11/15 09:40
-	392668	semiconductor integrated adj circuit	USPAT; US-PGPUB	2002/11/15 09:41
-	204	(pin! adj block) and (semiconductor integrated adj circuit)	USPAT; US-PGPUB	2002/11/15 09:41

-	104	((pin! adj block) and (semiconductor integrated adj circuit)) not (@ad>19950726 @rlad>19950726)	USPAT; US-PGPUB	2002/11/15 09:44
-	610869	solvent dissolv\$	USPAT; US-PGPUB	2002/11/15 09:45
-	34	((pin! adj block) and (semiconductor integrated adj circuit)) not (@ad>19950726 @rlad>19950726)) and (solvent dissolv\$)	USPAT; US-PGPUB	2002/11/15 10:38
-	8	wax with wafer with (cure or cured or curing)	USPAT; US-PGPUB	2002/11/15 10:41
-	315	Apiezon	USPAT; US-PGPUB	2002/11/15 10:41
-	16	Apiezon with wafer	USPAT; US-PGPUB	2002/11/15 10:41
-	13	(Apiezon with wafer) not (@ad>19950726 @rlad>19950726)	USPAT; US-PGPUB	2002/11/15 10:49
-	3	Apiezon with (cure cured curing)	USPAT; US-PGPUB	2002/11/15 10:50
-	1783	wax with (cure cured curing)	USPAT; US-PGPUB	2002/11/15 10:50
-	13	wafer same (wax with (cure cured curing))	USPAT; US-PGPUB	2002/11/15 10:51
-	5	(wafer same (wax with (cure cured curing))) not (wax with wafer with (cure or cured or curing))	USPAT; US-PGPUB	2002/11/15 10:51
-	1	("4904610").PN.	USPAT; US-PGPUB	2002/11/15 10:51